

# Product Qualification Report

## SPI07N65C3

CoolMOS™

### Description

This product qualification report describes the characteristics of the product with respect to quality and reliability.

The qualification sample selection was done on production lots which were manufactured and tested on standard production processes and meet the defined requirements.

The qualification test results of those products as outlined in this document are based on **JEDEC** for target applications and may reference existing qualification results of similar products. Such referencing is justified by the structural similarity of the products.

### Qualification Assessment

Fully qualified according to **JEDEC** for **Industrial Applications** and assessed as PASS

For further information about comparable products, please contact the nearest Infineon Technologies office ([www.infineon.com](http://www.infineon.com)).

**SPI07N65C3**  
**PG-TO220-3**  
**MSL: NA; through hole device**

**qualified since 2003**

**Electrical Stress Test Results:**

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
High Temperature Reverse Bias JESD22 A108	HTRB*	Ta ≥ 150°C V <sub>DS</sub> ≥ 520V	1000 h	4 x 45	0 / 180	PASS
High Temperature Gate Bias JESD22 A108	HTGB*	Ta = 150°C V <sub>GS</sub> = +/-20V	1000 h	4 x 45	0 / 180	PASS
Intermittent Operational Life Test MIL-STD 750 / Meth.1037	IOL*	Delta T =100K	10000 cyc	4 x 45	0 / 180	PASS
ESD (HBM) JESD22-A114	HBM	Class 1C 1000V to < 2000V				PASS
ESD (CDM) JESD22-C101	CDM	Class 1C 1000V to < 2000V				PASS

**Environmental Stress Test Results:**

Test Description	Abbr.	Condition	Duration	Lots/SS	Fail/Qty	Result
Temperature Cycling JESD22 A104	TC*	-55°C to +150°C	1000 cyc	4 x 45	0 / 180	PASS
Autoclave JESD22 A102	AC*	Ta = 121°C rh = 100%	96 h	4 x 45	0 / 180	PASS

**Mechanical Stress Test Results:**

Test Description	Abbr.	Condition	Duration	Lots	Fail/Qty	Result
Destructive Physical Analysis	DPA	samples from AC & TC		4	0 / 4	PASS

**Notes:**

\* For SMD devices reliability stress tests performed after preconditioning test (PC) according to JESD22

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**Do you have a question about this document?**

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**Document reference**

**n.a.**

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